

Density Gradient Minimization with Coupling-Constrained Dummy Fill for CMP Control

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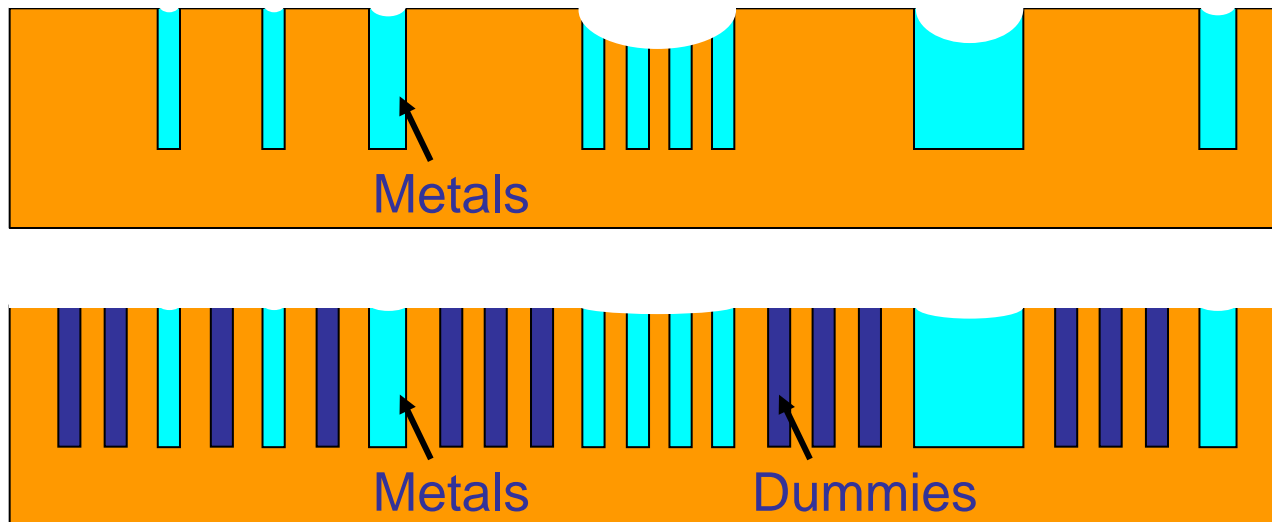


Outline

- . Introduction
- . Definition of Density Gradient
- . Previous Work
- . Multilevel Gradient Driven Dummy Fill Algorithm
- . Experimental Results
- . Conclusion and Future Work

Introduction

- Dummy fill is a general method to achieve layout uniformity before CMP (chemical-mechanical polishing)



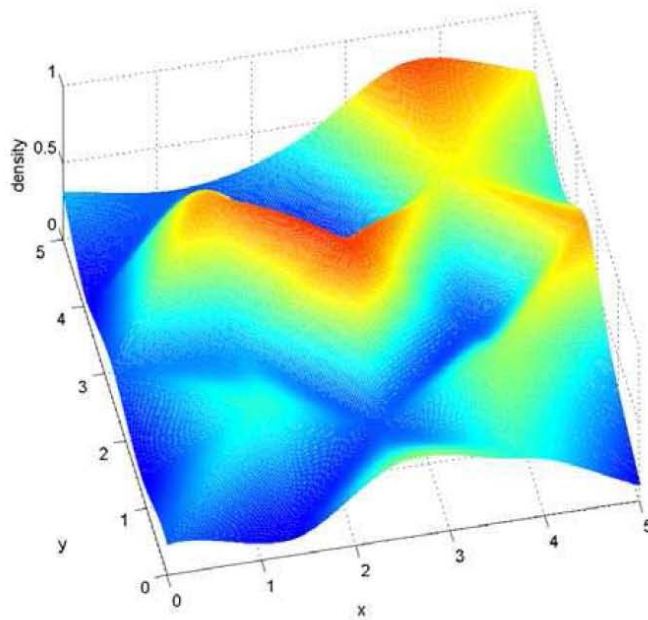
- Objectives for dummy fill:
 - minimize induced **coupling capacitance** of dummies
 - minimize **dummy counts**
 - minimize **density gradient** of metal density

Density Gradient

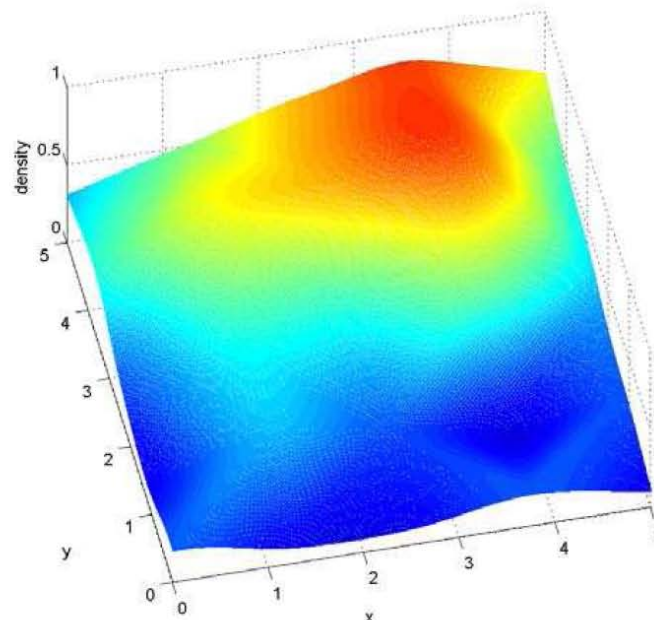
- . Gradient
 - means the rate of change of the function value in the direction of maximum change.
 - is generally used in solving optimization problem, such as the conjugate gradient method and the gradient descent method.
- . Density gradient of a tile
 - is the maximum density difference between this tile and the adjacent tiles.
- . Our work is the first work in the literature that simultaneously considers **coupling constraints**, **dummy counts**, and **density gradient**

Density Variation vs. Density Gradient

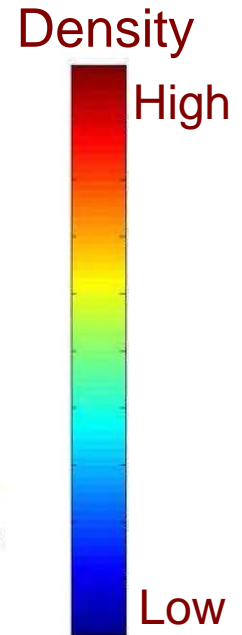
- Density gradient is different from density variation, but both of them would affect the post-CMP thickness.



density variation = 0.0523
density gradient = 0.7



density variation = 0.0523
density gradient = 0.4



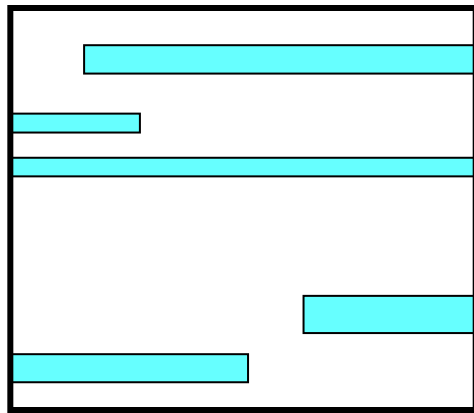
Considering density variation is not sufficient!

Previous Work

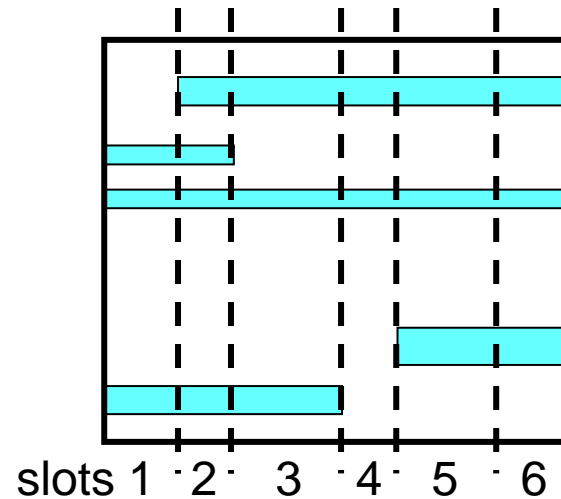
- Highlighted the importance of density variation
 - Chen *et al.*, “Closing the Smoothness and Uniformity Gap in Area Fill Synthesis,” *ISPD’02*.
- Considered wire density control during routing
 - Li *et al.*, “Multilevel Full-Chip Routing with Testability and Yield Enhancement,” *TCAD’07*
 - Chen *et al.*, “A Novel Wire-Density-Driven Full-Chip Routing System for CMP Variation Control,” *TCAD’09*
- Formed a tradeoff between excessive coupling and lithography cost
 - Deng *et al.*, “Coupling-Aware Dummy Metal Insertion for Lithography,” *ASPDAC’07*.
- Found the maximum dummy insertion regions with no coupling violation
 - Xiang *et al.*, “Fast Dummy-Fill Density Analysis With Coupling Constraints,” *TCAD’08*.

Previous Work: Coupling-Constrained Dummy Fill

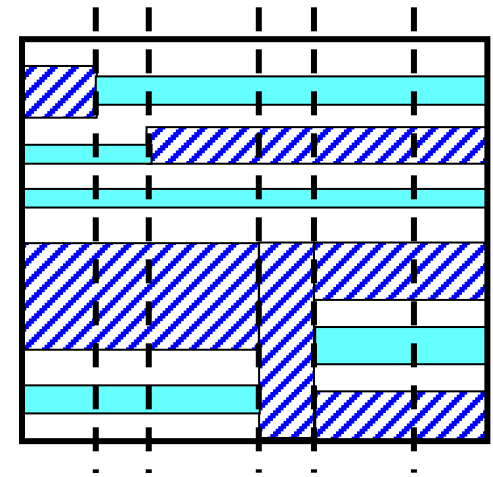
- CDF Algorithm presented in [Xiang *et al.* TCAD'08]



A layout



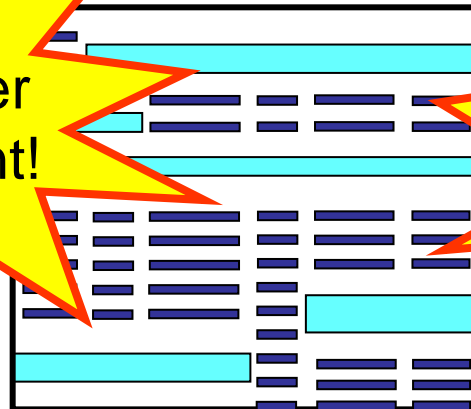
Slot partition by endpoints of segments



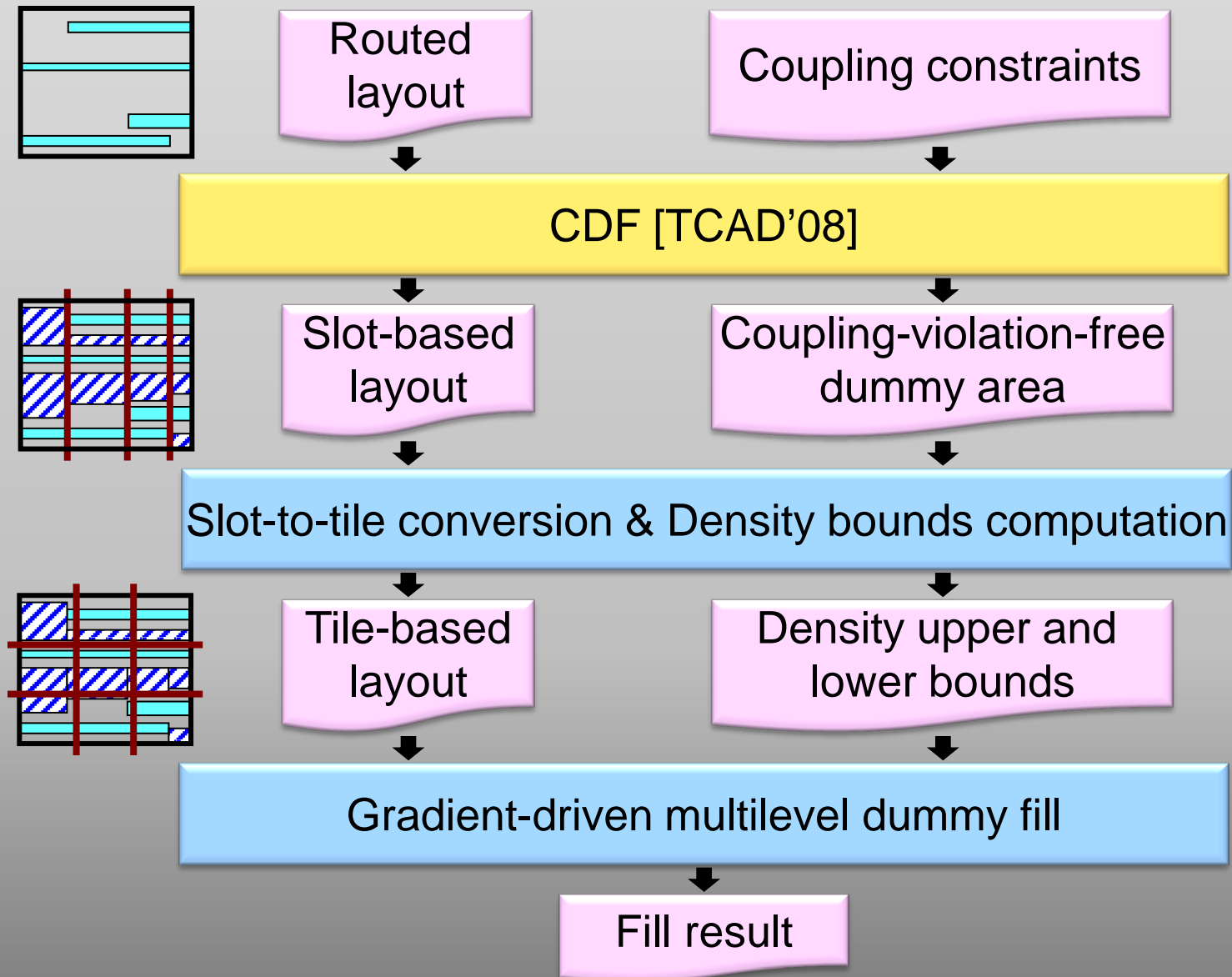
Coupling-free fill regions identification for each slot

Did not consider density gradient!

Used too many dummies!

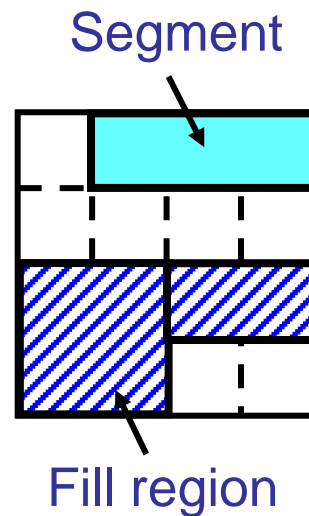
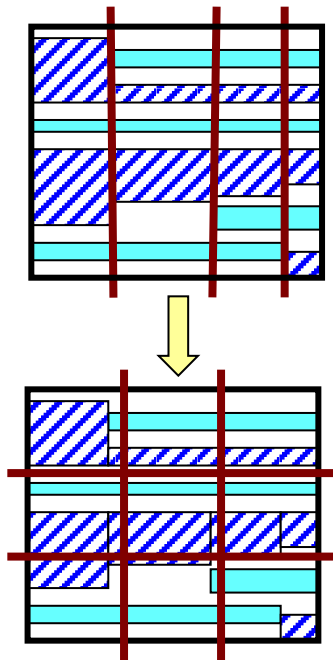


Our Algorithm Flow



Slot-to-Tile Conversion and Density Bounds Computation

- Convert slot-based layout to tile-based layout
- Compute tile density bounds in each tile satisfying both coupling and foundry density rules



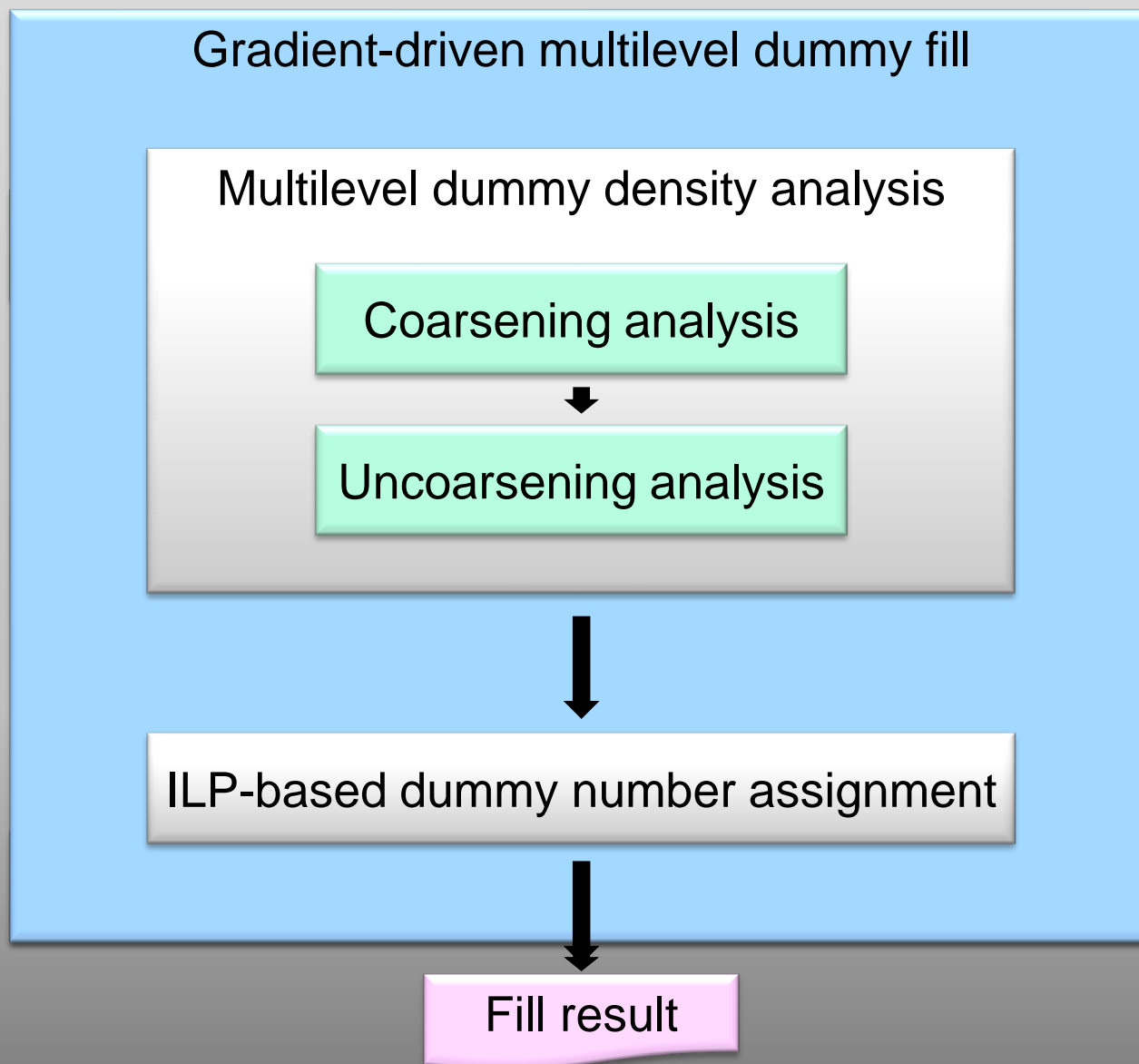
$$\text{Lower bound } B_l = \frac{\text{Cyan Tile}}{\text{Grid}}$$

$$\text{Upper bound } B_u = \frac{\text{Cyan Tile} + \text{Blue Hatched Tile}}{\text{Grid}}$$

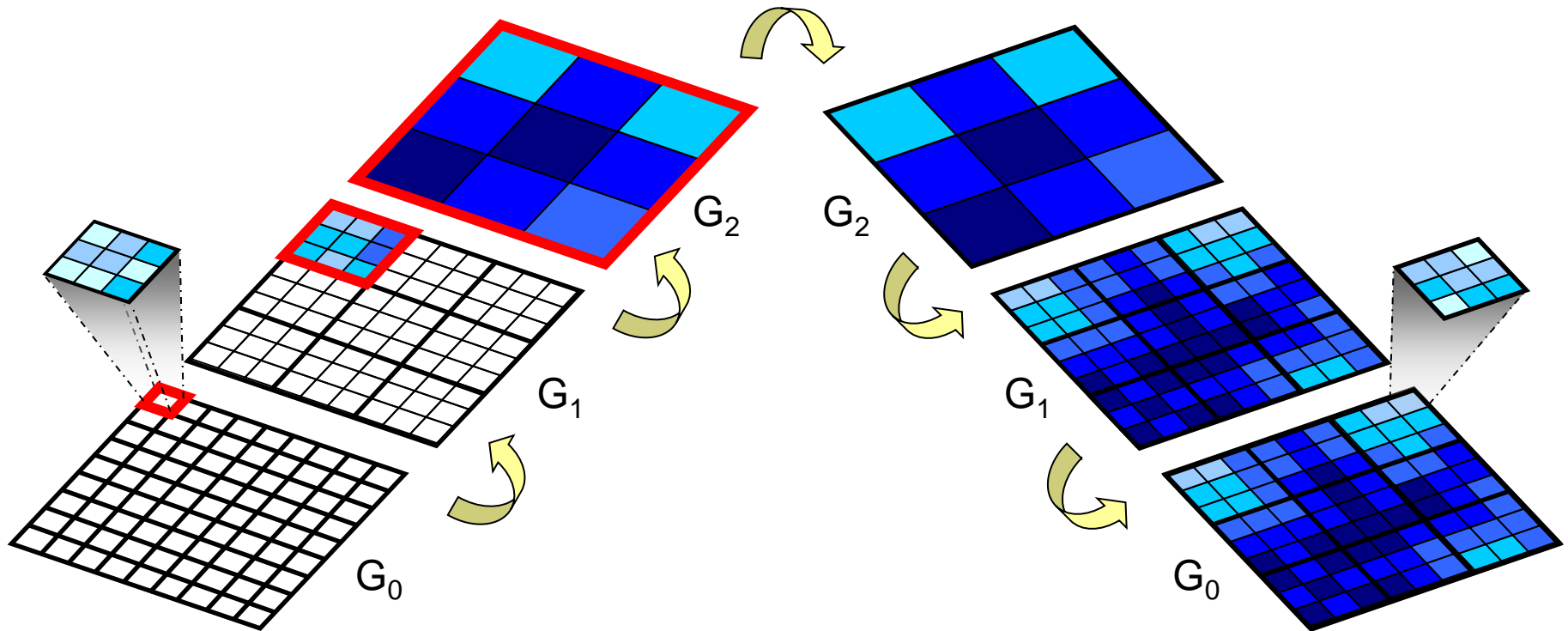
Further adjust the bounds according to foundry density rules

(B_l, B_u) guarantees no coupling and density rule violations in the following stages

Gradient-Driven Dummy Fill Flow



Multilevel Dummy Density Analysis

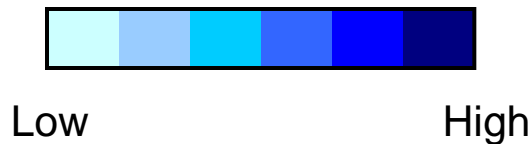


Coarsening

Metal Density

Uncoarsening

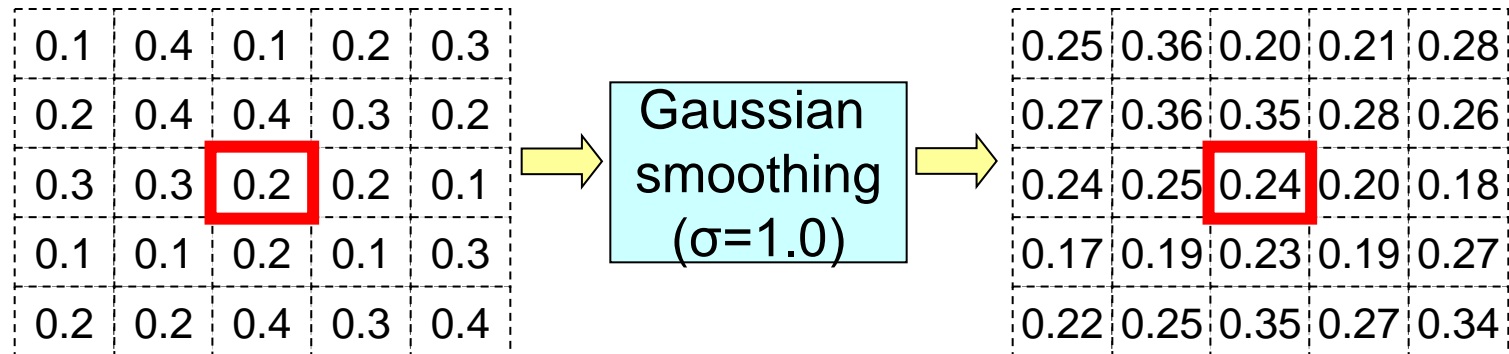
- (1) Gradient minimization by Gaussian smoothing
- (2) Density bounds update level by level



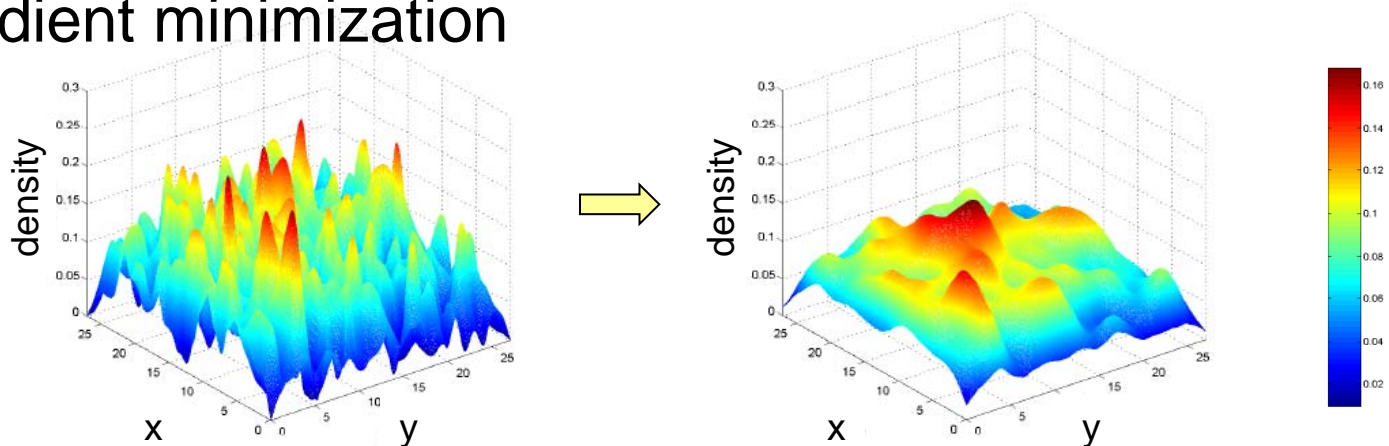
- (1) Density extraction
- (2) ILP-based dummy number assignment

Coarsening: Gradient Minimization

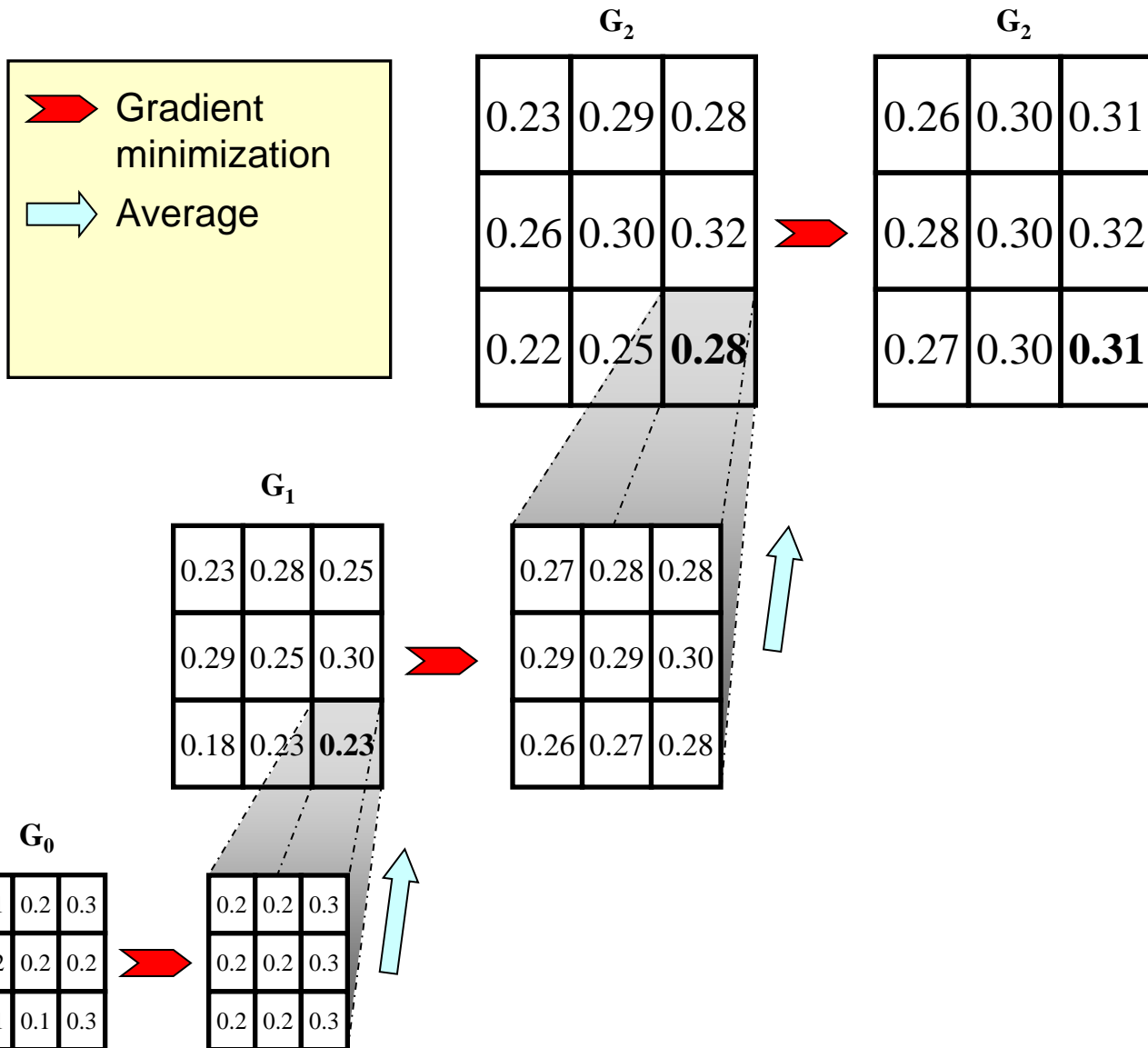
- Gaussian smoothing at tile $(\hat{x}, \hat{y}) = \sum D_c(x, y) g(x, y)$
 - $D_c(x, y)$: original density
 - $g(x, y)$: weighting function = $\frac{1}{2\pi\sigma^2} \exp\left(-\frac{(x-\hat{x})^2 + (y-\hat{y})^2}{2\sigma^2}\right)$



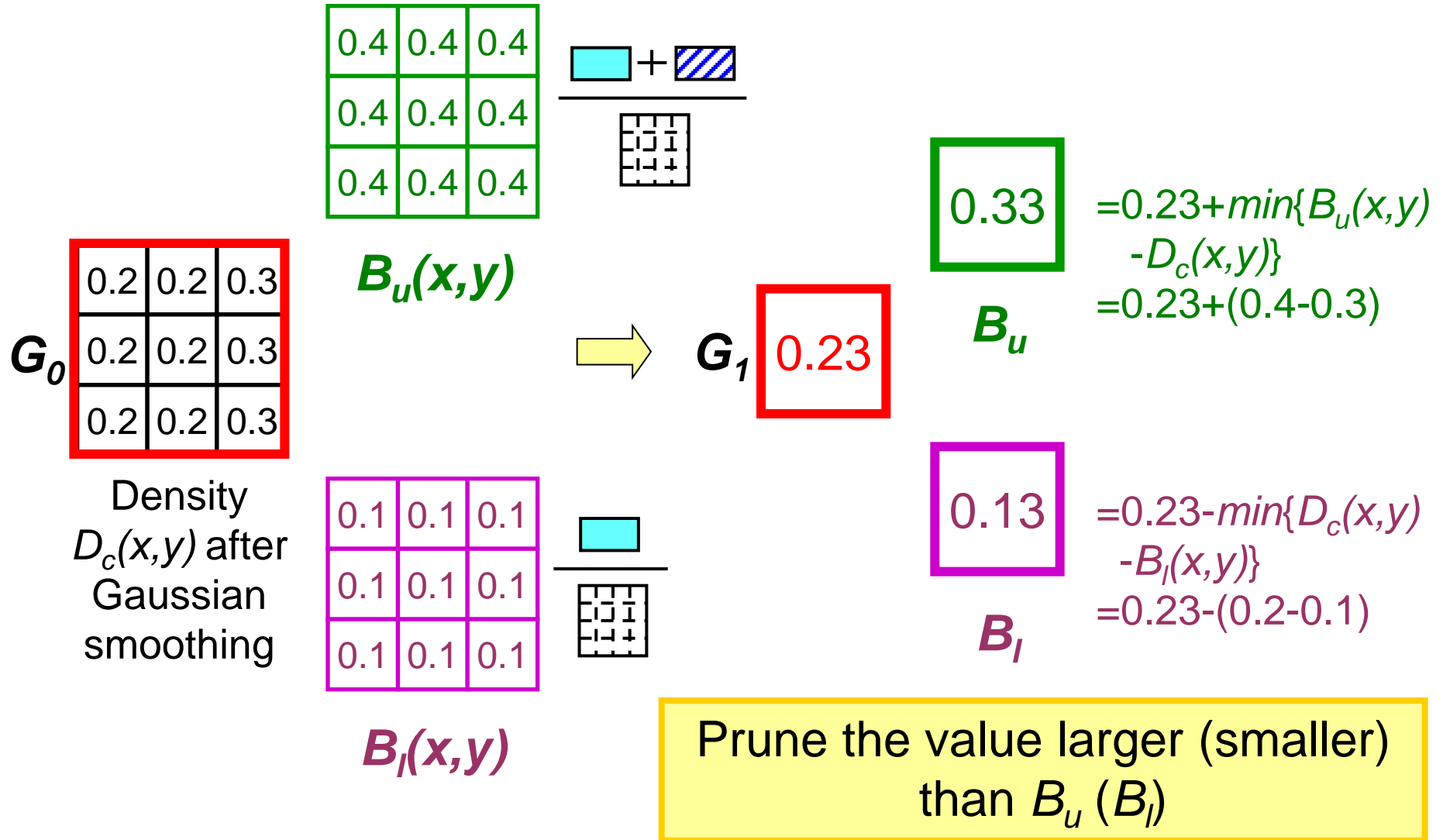
- Gaussian smoothing opens up a new direction for gradient minimization



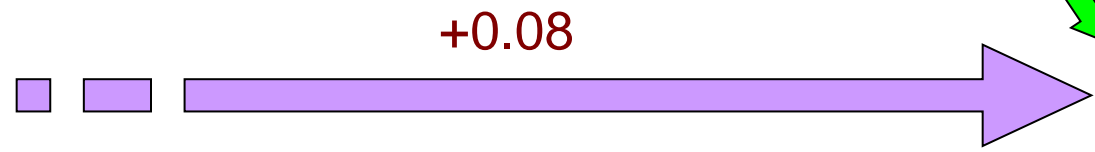
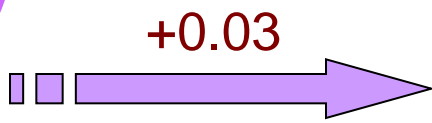
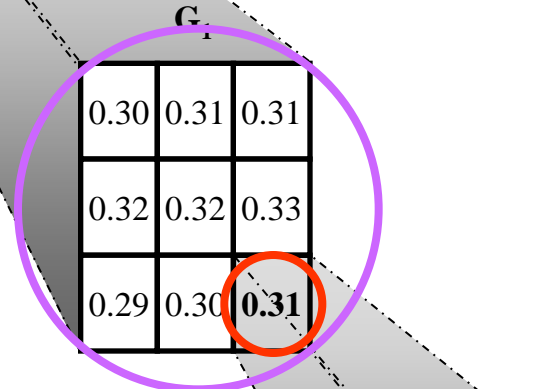
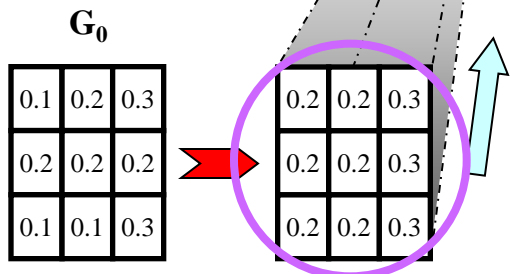
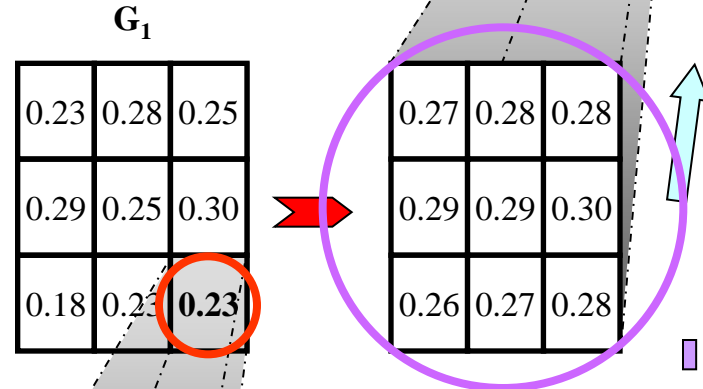
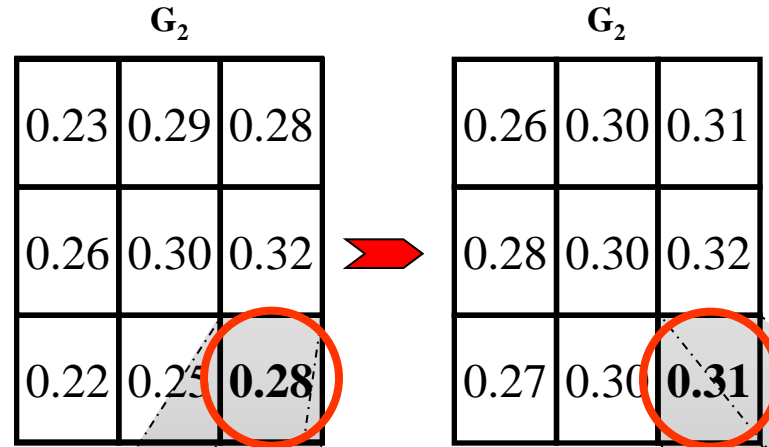
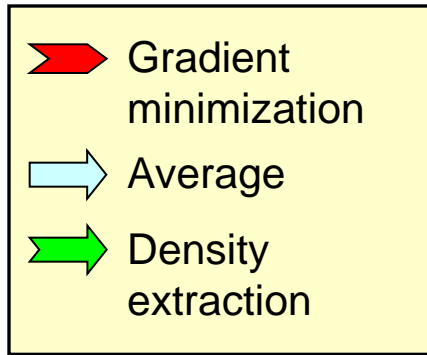
Coarsening: Density Analysis



Coarsening: Tile Density Bounds Update



Uncoarsening: Density Extraction



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ILP-based Dummy Number Assignment

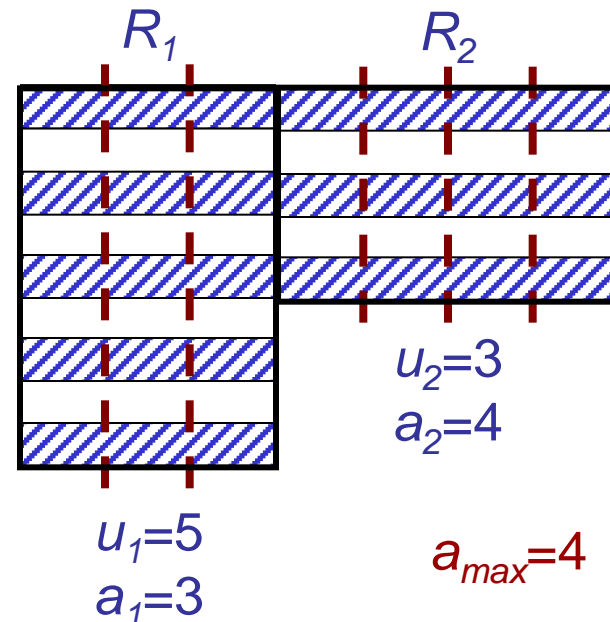
- Optimally insert minimal # of dummies to satisfy the desirable tile density d_d in a tile
- For the tile with n fill regions R_1, \dots, R_n ,

minimize $\sum_{i=1}^n r_i$

subject to $d_d a - \frac{1}{2} a_{\max} \leq \sum_{i=1}^n a_i r_i \leq d_d a + \frac{1}{2} a_{\max}$

$r_i \leq u_i, i = 1, \dots, n$

r_i : # of dummies in R_i
 d_d : dummy density of tile
 a : tile area
 a_i : area of one dummy in R_i
 a_{\max} : $\max \{a_i\}$
 u_i : max # of dummies in R_i



Experimental Setting

- . Programming language: C++
- . Workstation: 2.0 GHz AMD-64 with 8GB memory
- . ILP solver: Ip_solve
- . Parameters
 - Window size=3 × 3
 - Gaussian smoothing: $\sigma=1.0$
 - Foundry density lower and upper bounds: 20% and 60%
- . Test cases: MCNC and industrial Faraday benchmarks
- . Comparison with the CDFm algorithm [modified from CDF algorithm, TCAD'08] for all layers and layer 1
 - CDF algorithm: tries to insert as many dummies as possible
 - CDFm algorithm: also honors the density lower and upper bound rules

Benchmarks

. Routing results from Chen *et al.*, ICCAD'07

| Circuit | Size ($\mu\text{m} \times \mu\text{m}$) | #Layer | #Segment | #Level | Wire Density | | |
|----------|---|--------|----------|--------|--------------|--------|--------|
| | | | | | Avg. | Max | Std. |
| Mcc1 | 45000x39000 | 4 | 6199 | 4 | 9.85% | 47.80% | 9.46% |
| Mcc2 | 152400x152400 | 4 | 34371 | 4 | 10.80% | 54.50% | 9.90% |
| Struct | 4903x4904 | 3 | 10692 | 4 | 0.71% | 5.19% | 0.88% |
| Primary1 | 7522x4988 | 3 | 6889 | 4 | 0.54% | 9.10% | 0.94% |
| Primary2 | 10438x6488 | 3 | 28513 | 4 | 1.23% | 10.10% | 1.39% |
| S5378 | 435x239 | 3 | 9816 | 3 | 8.68% | 30.30% | 5.60% |
| S9234 | 404x225 | 3 | 8462 | 3 | 7.43% | 30.80% | 5.80% |
| S13207 | 660x365 | 3 | 21891 | 3 | 8.98% | 28.90% | 5.53% |
| S15850 | 705x389 | 3 | 25699 | 3 | 9.76% | 30.00% | 5.04% |
| S38417 | 1144x619 | 3 | 64045 | 3 | 8.32% | 32.10% | 4.87% |
| S38584 | 1295x672 | 3 | 85931 | 3 | 9.37% | 28.40% | 4.55% |
| Dma | 408.4x408.4 | 6 | 98018 | 5 | 15.60% | 71.40% | 16.30% |
| Dsp1 | 706.0x706.0 | 6 | 169867 | 5 | 10.70% | 55.10% | 13.40% |
| Dsp2 | 642.8x642.8 | 6 | 159525 | 5 | 11.00% | 60.50% | 13.20% |
| Risc1 | 1003.6x1003.6 | 6 | 237862 | 5 | 8.74% | 58.10% | 12.90% |
| Risc2 | 959.6x959.6 | 6 | 240978 | 5 | 8.82% | 50.60% | 11.90% |

Runtime and Inserted Dummy Counts

- Inserted dummy count is only 19% compared with CDF algorithm
- Timing overhead is only 19%

| Circuit | CDF | | Ours | |
|----------|------------|----------|-----------|----------|
| | #Dummy | Time (s) | #Dummy | Time (s) |
| Mcc1 | 1,262,298 | 160 | 163,821 | 171 |
| Mcc2 | 20,117,831 | 7249 | 4,282,218 | 7292 |
| Struct | 9,004,650 | 45 | 159,457 | 72 |
| Primary1 | 7,102,170 | 32 | 188,771 | 53 |
| Primary2 | 24,897,686 | 428 | 360,221 | 490 |
| S5378 | 269,916 | 21 | 53,527 | 22 |
| S9234 | 230,220 | 14 | 58,230 | 17 |
| S13207 | 657,861 | 73 | 141,723 | 76 |
| S15850 | 721,317 | 99 | 155,336 | 103 |
| S38417 | 2,100,467 | 330 | 248,582 | 337 |
| S38584 | 2,460,061 | 518 | 277,747 | 526 |
| Dma | 1,457,877 | 67 | 321,635 | 101 |
| Dsp1 | 3,648,742 | 290 | 1,012,893 | 330 |
| Dsp2 | 2,815,009 | 189 | 778,375 | 231 |
| Risc1 | 9,071,800 | 252 | 3,208,787 | 312 |
| Risc2 | 7,235,118 | 396 | 2,626,317 | 446 |
| Comp. | 1.00 | 1.00 | 0.19 | 1.19 |

Statistics of Metal Density (MCNC)

- The average density gradient are reduced by 70% and 59% among all layers and of layer 1, respectively

| Circuit | CDF Analysis Algorithm | | | | | | Ours | | | | | |
|----------|-------------------------------|--------|-------|-----------------------------|--------|--------|-------------------------------|--------|-------|-----------------------------|--------|-------|
| | Density Gradient among Layers | | | Density Gradient of Layer 1 | | | Density Gradient among Layers | | | Density Gradient of Layer 1 | | |
| | Avg. | Max | Std. | Avg. | Max | Std. | Avg. | Max | Std. | Avg. | Max | Std. |
| Mcc1 | 7.14% | 35.81% | 5.87% | 5.28% | 12.53% | 12.31% | 1.59% | 14.42% | 1.80% | 1.81% | 11.73% | 3.62% |
| Mcc2 | 4.40% | 14.67% | 2.39% | 3.53% | 8.16% | 5.07% | 2.23% | 16.84% | 2.54% | 2.80% | 12.07% | 5.21% |
| Struct | 1.41% | 5.75% | 1.34% | 0.56% | 5.67% | 2.74% | 0.16% | 0.33% | 0.07% | 0.19% | 0.33% | 0.13% |
| Primary1 | 2.38% | 13.09% | 2.54% | 1.61% | 10.34% | 4.60% | 0.14% | 0.32% | 0.08% | 0.17% | 0.32% | 0.15% |
| Primary2 | 1.22% | 3.97% | 0.97% | 0.20% | 1.25% | 2.44% | 0.12% | 0.25% | 0.05% | 0.14% | 0.25% | 0.10% |
| S5378 | 5.38% | 15.88% | 2.53% | 5.38% | 12.85% | 4.37% | 1.99% | 10.00% | 0.96% | 2.18% | 5.36% | 1.70% |
| S9234 | 6.31% | 20.79% | 3.18% | 6.27% | 14.01% | 5.52% | 2.02% | 8.67% | 1.11% | 2.25% | 4.26% | 1.96% |
| S13207 | 4.19% | 14.62% | 1.98% | 3.54% | 9.24% | 3.61% | 1.53% | 7.54% | 0.91% | 1.49% | 5.52% | 1.59% |
| S15850 | 4.13% | 12.50% | 1.92% | 3.64% | 8.81% | 3.43% | 1.38% | 9.90% | 0.79% | 1.36% | 2.41% | 1.38% |
| S38417 | 2.91% | 9.32% | 1.42% | 2.28% | 6.67% | 2.68% | 0.93% | 9.97% | 0.85% | 0.89% | 1.53% | 1.47% |
| S38584 | 2.80% | 8.97% | 1.29% | 2.41% | 7.08% | 2.34% | 0.79% | 8.24% | 0.68% | 0.79% | 1.38% | 1.18% |
| Comp. | 1.00 | 1.00 | 1.00 | 1.00 | 1.00 | 1.00 | 0.30 | 0.56 | 0.39 | 0.41 | 0.47 | 0.38 |

Statistics of Metal Density (Faraday)

- The average density gradient are reduced by 40% and 91% among all layers and of layer 1, respectively

| Circuit | CDF Analysis Algorithm | | | | | | Ours | | | | | |
|---------|-------------------------------|--------|-------|-----------------------------|--------|-------|-------------------------------|--------|-------|-----------------------------|-------|-------|
| | Density Gradient among Layers | | | Density Gradient of Layer 1 | | | Density Gradient among Layers | | | Density Gradient of Layer 1 | | |
| | Avg. | Max | Std. | Avg. | Max | Std. | Avg. | Max | Std. | Avg. | Max | Std. |
| Dma | 3.39% | 19.50% | 3.30% | 1.77% | 10.22% | 9.01% | 2.23% | 21.45% | 3.10% | 0.60% | 1.01% | 8.57% |
| Dsp1 | 2.90% | 24.33% | 3.69% | 2.87% | 24.33% | 9.03% | 1.49% | 20.08% | 2.50% | 0.14% | 0.57% | 6.95% |
| Dsp2 | 2.66% | 26.81% | 3.62% | 2.85% | 26.81% | 8.88% | 1.24% | 17.27% | 1.97% | 0.14% | 0.59% | 5.53% |
| Risc1 | 2.66% | 21.15% | 3.52% | 2.74% | 18.79% | 8.62% | 1.77% | 21.15% | 3.12% | 0.14% | 0.40% | 8.62% |
| Risc2 | 2.98% | 26.49% | 3.92% | 2.67% | 17.95% | 9.64% | 2.02% | 26.49% | 3.57% | 0.15% | 0.45% | 9.88% |
| Comp. | 1.00 | 1.00 | 1.00 | 1.00 | 1.00 | 1.00 | 0.60 | 0.90 | 0.79 | 0.09 | 0.03 | 0.88 |

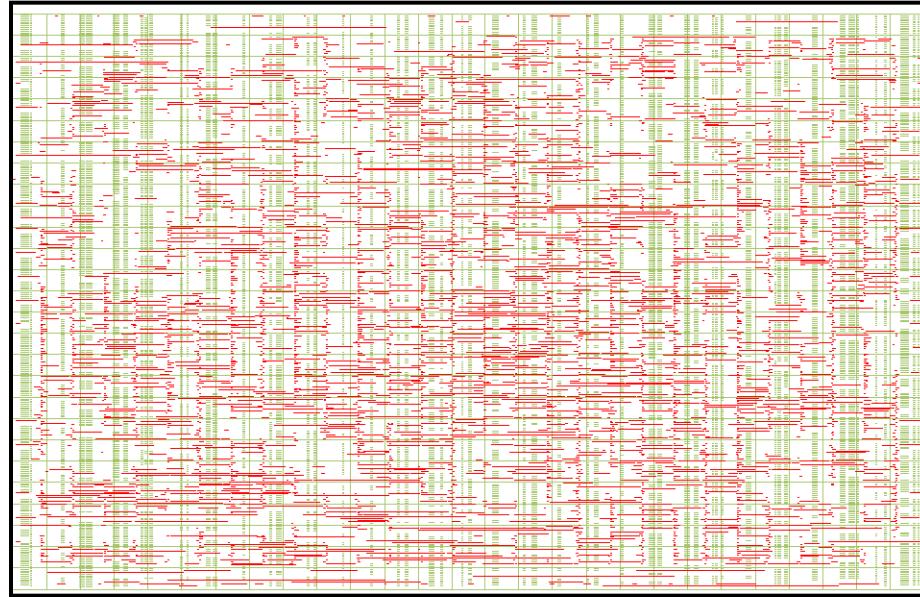
- Overall comparison (MCNC+Faraday)

| Circuit | CDF Analysis Algorithm | | | | | | Ours | | | | | |
|---------|-------------------------------|------|------|-----------------------------|------|------|-------------------------------|------|------|-----------------------------|------|------|
| | Density Gradient among Layers | | | Density Gradient of Layer 1 | | | Density Gradient among Layers | | | Density Gradient of Layer 1 | | |
| | Avg. | Max | Std. | Avg. | Max | Std. | Avg. | Max | Std. | Avg. | Max | Std. |
| Comp. | 1.00 | 1.00 | 1.00 | 1.00 | 1.00 | 1.00 | 0.37 | 0.66 | 0.51 | 0.32 | 0.31 | 0.53 |

Comparison of S5378 Layer 1 Filling Results

CDFm algorithm

Metal density = 27.15%
Fill inserted = 100%

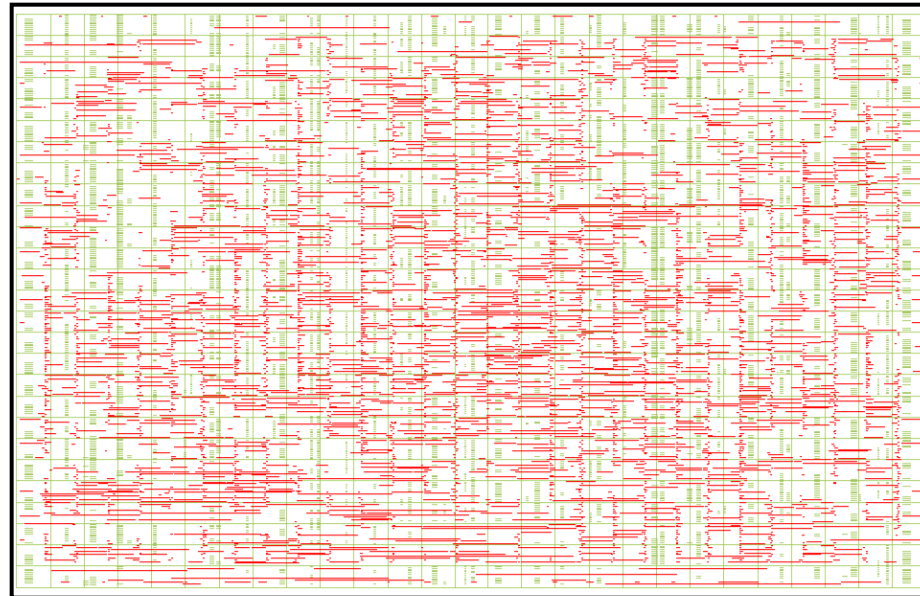


— wires

— fills

Ours

Metal density = 21.97%
Fill inserted = 20%



Conclusions and Future Work

- . Presented an effective and efficient dummy fill algorithm considering both gradient minimization and coupling constraints
 - Reduced 63% of density gradient among all layers
 - Saved 91% dummy counts
- . Gaussian smoothing is effective for gradient-minimization dummy fill
 - Point out a new research direction on this topic
- . Future work: simultaneously gradient and coupling capacitance optimization



Q & A

Thank You!

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